PACKAGE OUTLINE

RVM0076A

VQFNP-MR - 0.9 mm max height

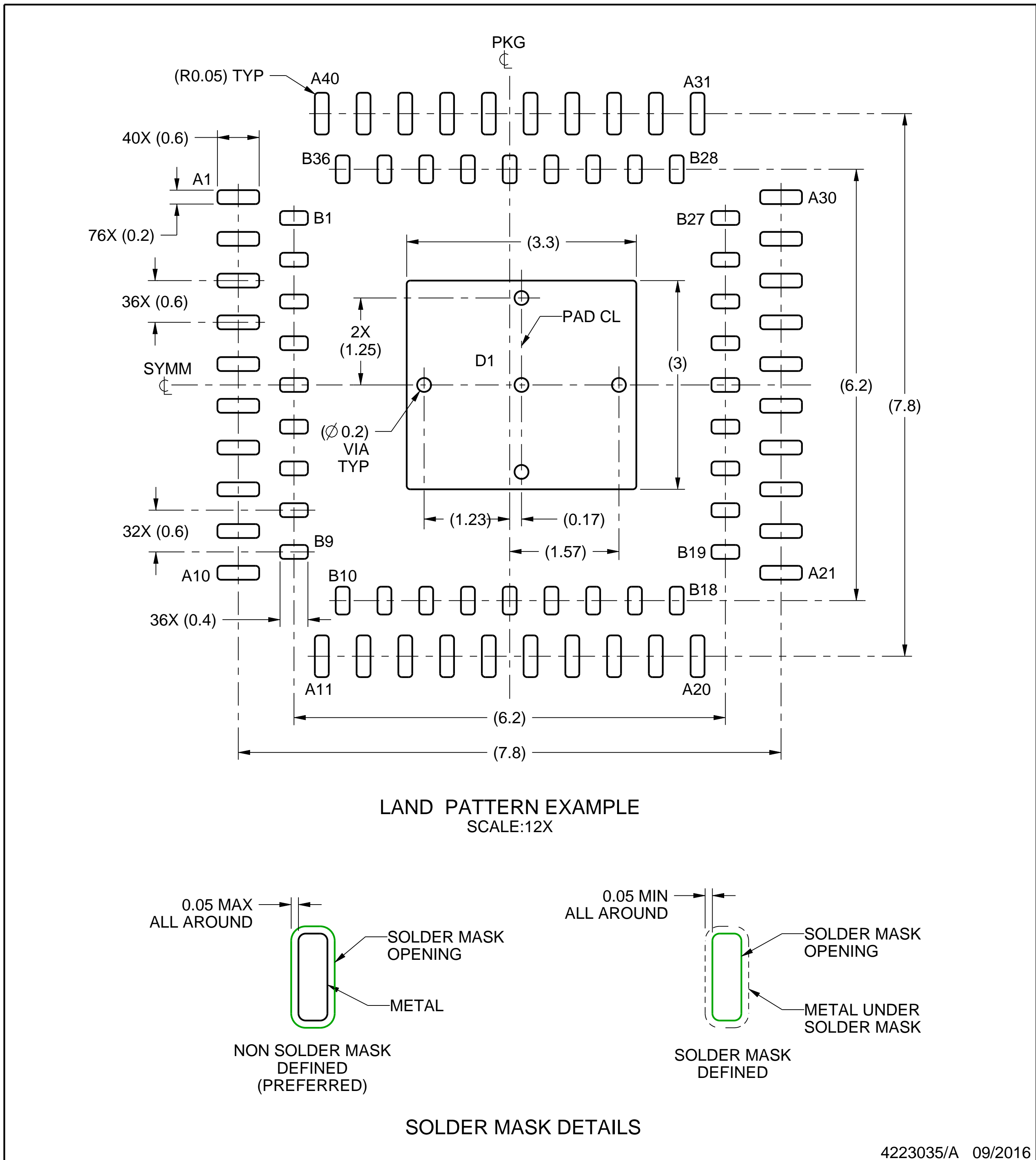
PLASTIC QUAD FLATPACK - NO LEAD

B
8.1
7.9
A
PIN 1 ID
8.1
7.9
4X 45° X 0.60
0.24
0.9 MAX
C
SEATING PLANE
(0.2) TYP
0.05
0.00
0.08 C
3.3±0.1
(0.17)
A11
A20
THERMAL PAD CL
32X 0.6
A10
B10
B18
A21
B9
B19
3.1 TYP
4X
5.4
4X
4.8
D1
SYMM
℄
3±0.1
PIN 1 ID
EXPOSED
THERMAL PAD
B1
B27
A1
A30
B36
B28
36X 0.6
76X 0.25
0.15
0.1Ⓜ C B A
0.05Ⓜ C
A40
A31
PKG
℄
76X 0.5
0.3
3.1 TYP

4223035/A 09/2016

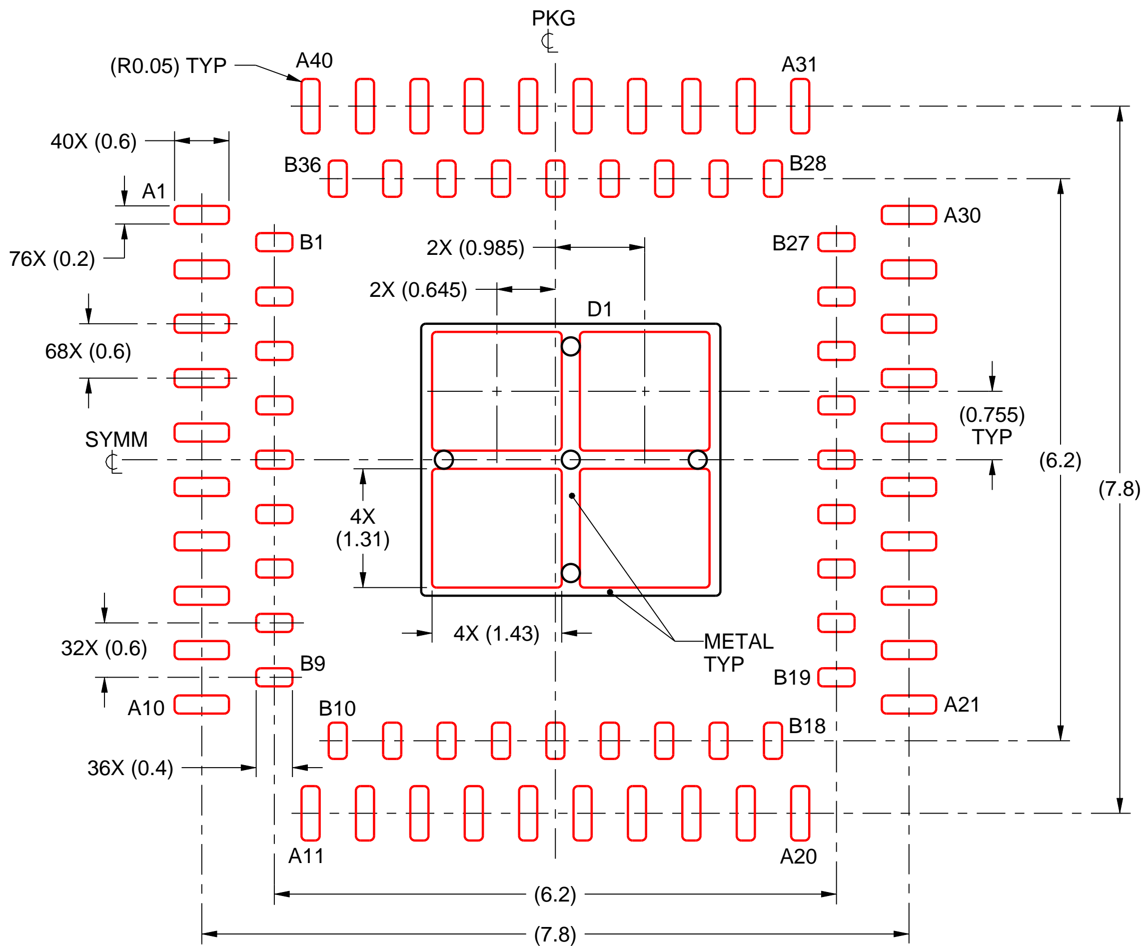
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD D1
76% PRINTED SOLDER COVERAGE BY AREA
SCALE:12X

4223035/A 09/2016

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.